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Abstract of the Disclosure

[0063] A one-time feedback CMP process control method which contributes to uniformity in the quantity of material removed from wafers in a lot during semiconductor processing and is suitable for complex processes such as STI (shallow trench isolation) fabrication procedures, is disclosed. The method includes providing a plurality of wafers having a set of pilot wafers and a set of remaining wafers, polishing each of the pilot wafers according to an original process time, determining a compensation time for the pilot wafers, determining an update time by adding the compensation time to the original process time and polishing the set of remaining wafers according to the update time.